



## Power line chokes

Current-compensated D core double chokes  
250 V AC, 3.3 ... 100 mH, 0.35 ... 1.8 A, +40 °C

**Series/Type:**            **B82731M/H**

**Date:**                    December 2016

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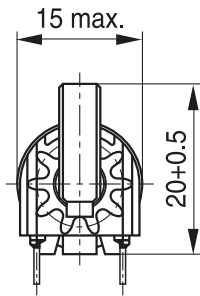
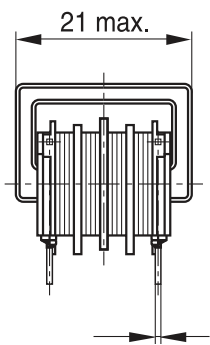
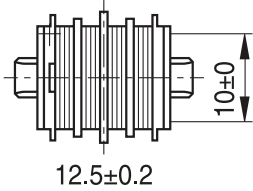
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### Dimensional drawings and pin configurations

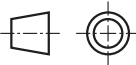
Vertical version (B82731M)

Horizontal version (B82731H)



IND0284-2

Part tolerances to ISO 2768-cL / ISO 8015.  
 Size ISO 14405 (E)  
 All dimensions in mm



IND1276-L-E

**Technical data and measuring conditions**

Rated voltage $V_R$	250 V AC (50/60 Hz)
Test voltage $V_{test}$	1500 V AC, 2 s (line/line)
Rated temperature $T_R$	+40 °C
Rated current $I_R$	Referred to 50 Hz and rated temperature
Rated inductance $L_R$	Measured with Agilent 4284A at 10 kHz, 0.1 mA, +20 °C. Inductance is specified per winding.
Inductance tolerance	-30/+50% at +20 °C
Inductance decrease $\Delta L/L_0$	< 10% at DC magnetic bias with $I_R$ , +20 °C
Stray inductance $L_{stray,typ}$	Measured with Agilent 4284A at 10 kHz, 5 mA, +20 °C, typ. values
DC resistance $R_{typ}$	Measured at +20 °C, typical values, specified per winding
Solderability (lead-free)	Sn96.5Ag3.0Cu0.5: +(245 ±3) °C, (3 ±0.3) s Wetting of soldering area ≥ 95% (to IEC 60068-2-20, test Ta)
Resistance to soldering heat (wave soldering)	+(260 ±5) °C, (10 ±1) s (to IEC 60068-2-20, test Tb)
Climatic category	40/125/56 (to IEC 60068-1)
Storage conditions (packaged)	-25 °C ... +40 °C, ≤ 75% RH
Weight	Approx. 8 g
Approvals	IEC EN 60938-2, UL 1283 (E70122)

**Characteristics and ordering codes**

$I_R$ A	$L_R$ mH	$L_{stray,typ}$ μH	$R_{typ}$ mΩ	Ordering code		Approvals	
				Vertical version	Horizontal version		
0.35	100	1000	4500	B82731M2351A030	B82731H2351A030	×	×
0.4	68	700	3000	B82731M2401A033	B82731H2401A033	×	×
0.5	47	470	2000	B82731M2501A030	B82731H2501A030	×	×
0.6	39	390	1500	B82731M2601A030	B82731H2601A030	×	×
0.7	27	270	1000	B82731M2701A030	B82731H2701A030	×	×
0.8	22	220	800	B82731M2801A030	B82731H2801A030	×	×
0.9	15	150	600	B82731M2901A030	B82731H2901A030	×	×
1.1	10	100	400	B82731M2112A030	B82731H2112A030	×	×
1.3	6.8	70	280	B82731M2132A030	B82731H2132A030	×	×
1.8	3.3	35	140	B82731M2182A030	B82731H2182A030	×	×

× = approval granted

Sample kit available. Ordering code: B82731X001

For more information refer to chapter "Sample kits".

**Impedance  $|Z|$  versus frequency  $f$**   
 measured with windings in parallel at +20 °C,  
 typical values



**Current derating  $I_{op}/I_R$**   
 versus ambient temperature  $T_A$



## Cautions and warnings

- Please note the recommendations in our Inductors data book (latest edition) and in the data sheets.
  - Particular attention should be paid to the derating curves given there.
  - The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pin, not the housing.
- If the components are to be washed varnished it is necessary to check whether the washing varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. In particular, it is possible for washing varnish agent residues to have a negative effect in the long-term on wire insulation.  
Washing processes may damage the product due to the possible static or cyclic mechanical loads (e.g. ultrasonic cleaning). They may cause cracks to develop on the product and its parts, which might lead to reduced reliability or lifetime.
- The following points must be observed if the components are potted in customer applications:
  - Many potting materials shrink as they harden. They therefore exert a pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
  - It is necessary to check whether the potting material used attacks or destroys the wire insulation, plastics or glue.
  - The effect of the potting material can change the high-frequency behaviour of the components.
- Ferrites are sensitive to direct impact. This can cause the core material to flake, or lead to breakage of the core.
- Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.

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